

U.S. Patent Application Serial No. 10/634,230
Reply to Office Action dated May 24, 2006

In the Substitute Specification

On page 2, please replace the ^{fourth} ~~first~~ paragraph with the following rewritten paragraph:

ycc
10/31/06

To achieve the above objects, there is provided a forming method using a thermal transfer printing sheet, comprising the steps of a step (S100) for forming a base material 10 using a resin, a step (S300) for printing a ~~partial deposition~~ thermal transfer printing sheet 21 to form a conduction film 24 on a surface of the formed base material 10, wherein the conduction film 24 includes a metallic conduction film 20 and an ink conduction film 22, or partially printing a gold or silver thermal transfer printing sheet 21 on a surface of said substrate, a step (S400) for heating a surface of the printed base material 10 and depressing ~~a part of a conduction film 24 transferred to the ink conduction film 22~~ the ink conduction film 22 on the base material 10 and a part of the lower base material 10 underneath the ink conduction film 22 by thermal diffusion, and a step (S500) for cooling the base material 10.

On page 6, please replace the ^{second} ~~third~~ paragraph with the following rewritten paragraph:

10/31/06

The surface of the printed base material 10 is heated, and ~~a part of the printed conduction film 24~~ the ink conduction film 22 and a part of the lower base material 10 underneath the ink conduction film 22 are depressed by the thermal melting method (S400).

On page 6, please replace the ^{sixth} ~~seventh~~ paragraph with the following rewritten paragraph:

ycc
10/31/06

The time of heating by the heating unit 50 is about 3~5 seconds. At this time, since the heat is blocked from the metallic conduction film 20 among the printed conduction film 24, and the part of the lower base material 10 underneath the metallic conduction film 20 maintains an original shape. ~~The~~ Since the heat is not blocked to the ink conduction film 22 among the printed conduction film 24, the ink conduction film 22 and the part of the lower base material 10

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underneath the ink conduction film 22 are heat-melted for thereby forming a depression portion 23. A certain protruded surface corresponding to the pattern of the partial deposition thermal transfer printing sheet 21, or the pattern that the gold or silver thermal transfer printing sheet 21 partially printed using the engraving roller is formed in the base material 10 based on a difference between the heated and melted portion and the non-melted portion.

Amendments to the Specification:

Page 1, after the title of the invention, insert the following section:

--CROSS REFERENCE TO RELATED APPLICATIONS:

This is a U.S. National Phase Application under 35 U.S.C. § 371 of International Application No. PCT/AU01/01262 filed October 9, 2001, which was published Under PCT Article 21(2), which claims priority to Australian Application No. PR0616, filed October 10, 2000, the entire contents of which are incorporated herein by reference.--

Please replace the paragraph beginning at page 9, line 14, with the following rewritten paragraph:

--Preferably the support member is in the form of an ~~elasticated~~elasticized sleeve.--

Please replace the paragraph beginning at page ¹⁰~~9~~, line ⁵~~14~~, with the following rewritten paragraph: 10-31-06
DLD

--The embodiment of the invention includes detectors in the form of a transducer array 10 and an actuator array 12. The transducer array 10 and actuator array 12 are carried on a support member 50 (shown in Figure 4) and which can be in the form of an ~~elasticated~~elasticized sleeve, band or the like which is to be worn by a patient. The transducer array 10 and actuator array 12 are connected to a processing means 20 carried on a circuit board 21 shown in dotted lines in Figure 1 by a communication link such as a cable 11. However, other forms of communication can be used such as electro-magnetic radiation transmission for wireless communication such as infrared data transmission.--